



PTO/SE/36 (11-98)

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CERTIFICATE OF EXPRESS MAIL UNDER 37 C.F.R. §1.10 "Express Mail" mailing label number: EL726369888US DATE OF DEPOSIT: February 8, 2001 I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 C.F.R. §1.10 on the date indicated above and is addressed to: Assistant Commissioner for Patents Washington, DC 20231  Derrick Brown		REQUEST TO RESCIND PREVIOUS NONPUBLICATION REQUEST 35 U.S.C. 122(b)(2)(B)(II)	
Application No.	Unknown		
Filing Date	February 7, 2001		
First Named Inventor:	Anantha R. Sethuraman et al.		
Atty Docket No.	5298-02501		
Group Art Unit	Unknown		
Examiner	Unknown		
Title:	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT		

I hereby rescind the previous request that the above-identified application not be published under 35 U.S.C. 122(b).	
February 8, 2001 Date	 Kevin L. Daffer, Reg. No. 34,146
This request must be signed in compliance with 37 CFR 1.33(b).	

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